

Title (en)

MOULDING COMPOUND BASED ON THERMOSETTING RESIN MATERIAL CONTAINING FIBRES

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Application

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Abstract (en)

[origin: EP0197618A1] The invention relates to a moulding compound based on thermosetting resin material and optionally fibres, fillers, curing catalysts and further usual additives, and is characterized in that the moulding compound comprises a mixture of at least two thermosetting resins of which a first resin is in a partly cured state, and of which a second resin is not, or less than the first resin in a partly cured state.

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